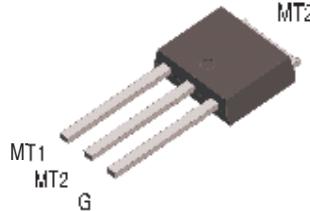
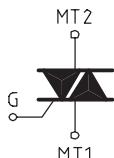


## HIGH COMMUTATION TRIAC

<b>IPAK (Plastic)</b>  	<b>On-State Current</b> 8 Amp	<b>Gate Trigger Current</b> ≤ 50 mA
	<b>Off-State Voltage</b> 200 V ÷ 800 V	
<p>This series of TRIACs uses a high performance PNPN technology.</p> <p>These parts are intended for general purpose AC switching applications with highly inductive loads.</p>		

### Absolute Maximum Ratings, according to IEC publication No. 134

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
$I_{T(RMS)}$	RMS On-state Current (full sine wave)	All Conduction Angle, $T_C = 95^\circ\text{C}$	8	A
$I_{TSM}$	Non-repetitive On-State Current	Full Cycle, 60 Hz ( $t = 16.7 \text{ ms}$ )	84	A
$I_{TSM}$	Non-repetitive On-State Current	Full Cycle, 50 Hz ( $t = 20 \text{ ms}$ )	80	A
$I^2t$	Fusing Current	$t_p = 10 \text{ ms}$ , Half Cycle	32	$\text{A}^2\text{s}$
$I_{GM}$	Peak Gate Current	20 $\mu\text{s}$ max. $T_j = 125^\circ\text{C}$	4	A
$P_{G(AV)}$	Average Gate Power Dissipation	$T_j = 125^\circ\text{C}$	1	W
$di/dt$	Critical rate of rise of on-state current	$I_G = 2x I_{GT}$ , $t_r \leq 100\text{ns}$ $f = 120 \text{ Hz}$ , $T_j = 125^\circ\text{C}$	50	$\text{A}/\mu\text{s}$
$T_j$	Operating Temperature		(-40 +125)	$^\circ\text{C}$
$T_{stg}$	Storage Temperature		(-40 +150)	$^\circ\text{C}$
$T_{sld}$	Soldering Temperature	10s max	260	$^\circ\text{C}$

SYMBOL	PARAMETER	VOLTAGE					Unit
		B	D	M	S	N	
$V_{DRM}$	Repetitive Peak Off State Voltage	200	400	600	700	800	V
$V_{RRM}$							

## HIGH COMMUTATION TRIAC

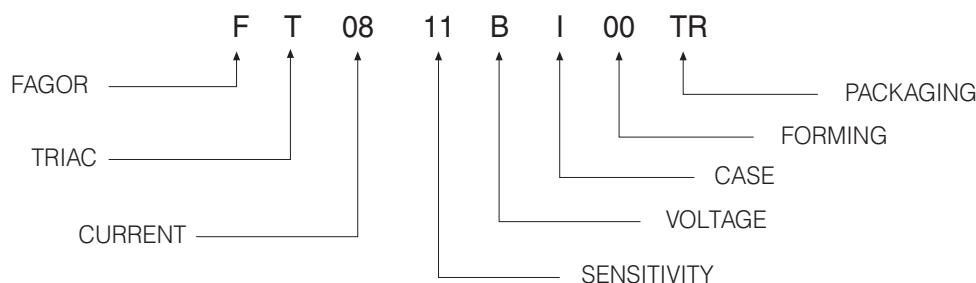
### Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	Quadrant		SENSITIVITY			Unit
					11	14	16	
$I_{GT}^{(1)}$	Gate Trigger Current	$V_D = 12 \text{ V}_{DC}$ , $R_L = 33\Omega$ , $T_j = 25^\circ\text{C}$	Q1÷Q3	MAX	25	35	50	mA
$V_{GT}$	Gate Trigger Voltage	$V_D = 12 \text{ V}_{DC}$ , $R_L = 33\Omega$ , $T_j = 25^\circ\text{C}$	Q1÷Q3	MAX			1.3	V
$V_{GD}$	Gate Non Trigger Voltage	$V_D = V_{DRM}$ , $R_L = 3.3\text{K}\Omega$ , $T_j = 125^\circ\text{C}$	Q1÷Q3	MIN			0.2	V
$I_H^{(2)}$	Holding Current	$I_T = 100 \text{ mA}$ , Gate open, $T_j = 25^\circ\text{C}$		MAX	25	35	50	mA
$I_L$	Latching Current	$I_G = 1.2 I_{GT}$ , $T_j = 25^\circ\text{C}$	Q1, Q3	MAX	40	50	70	mA
$dV/dt^{(2)}$	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$ , Gate open $T_j = 125^\circ\text{C}$	Q2	MAX MIN	50 200	60 500	80 1000	V/μs
$(dI/dt)c^{(2)}$	Critical Rate of Current Rise	$(dV/dt)c = 0.1 \text{ V}/\mu\text{s}$ $T_j = 125^\circ\text{C}$ $(dV/dt)c = 10 \text{ V}/\mu\text{s}$ $T_j = 125^\circ\text{C}$ without snubber $T_j = 125^\circ\text{C}$		MIN MIN MIN	- - 4.0	- - 4.5	- - 7	A/ms
$V_{TM}^{(2)}$	On-state Voltage	$I_T = 11 \text{ Amp}$ , $t_p = 380 \mu\text{s}$ , $T_j = 25^\circ\text{C}$		MAX			1.6	V
$V_{t(0)}^{(2)}$	Threshold Voltage	$T_j = 125^\circ\text{C}$		MAX			0.85	V
$r_d^{(2)}$	Dynamic Resistance	$T_j = 125^\circ\text{C}$		MAX			90	mΩ
$I_{DRM}/I_{RRM}$	Off-State Leakage Current	$V_D = V_{DRM}$ , $T_j = 125^\circ\text{C}$ $V_R = V_{RRM}$ , $T_j = 25^\circ\text{C}$		MAX MAX			1 5	mA μA
$R_{th(j-c)}$	Thermal Resistance Junction-Case	for AC 360° conduction angle					1.8	°C/W
$R_{th(j-a)}$							100	°C/W

(1) Minimum  $I_{GT}$  is guaranteed at 5% of  $I_{GT}$  max.

(2) For either polarity of electrode MT2 voltage with reference to electrode MT1.

### PART NUMBER INFORMATION



## HIGH COMMUTATION TRIAC

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle)

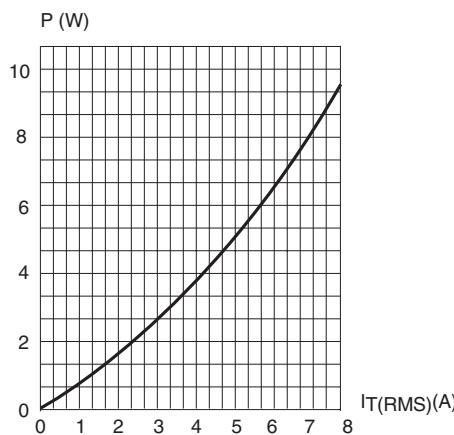


Fig. 3: Relative variation of thermal impedance versus pulse duration

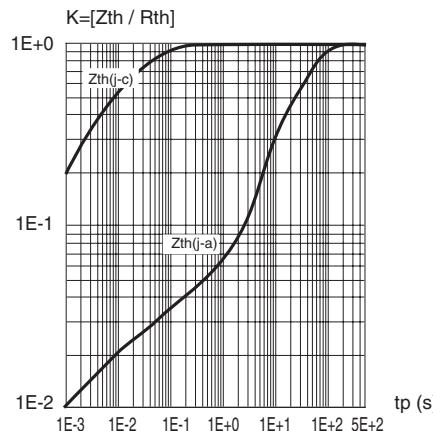


Fig. 5: Surge peak on-state current versus number of cycles

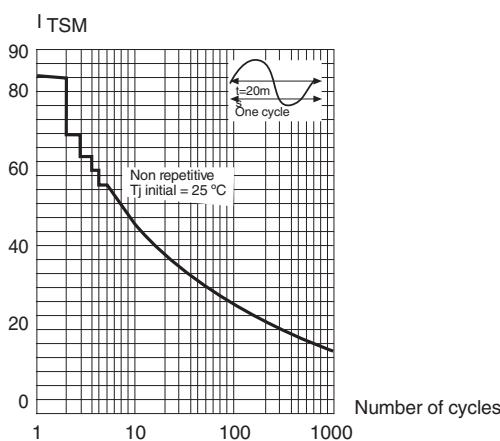


Fig. 2: RMS on-state current versus case temperature (full cycle)

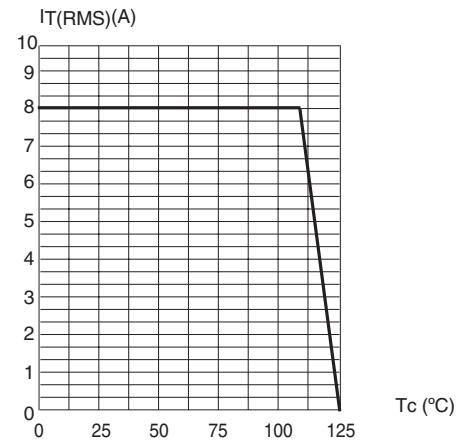


Fig. 4: On-state characteristics (maximum values)

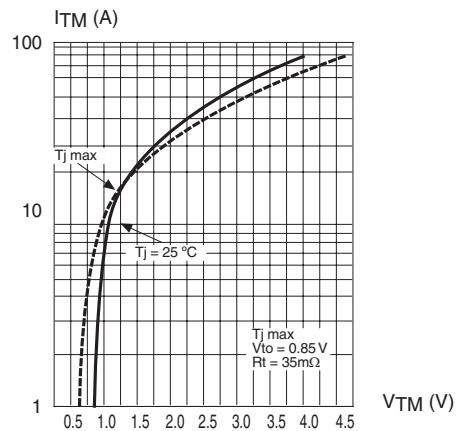
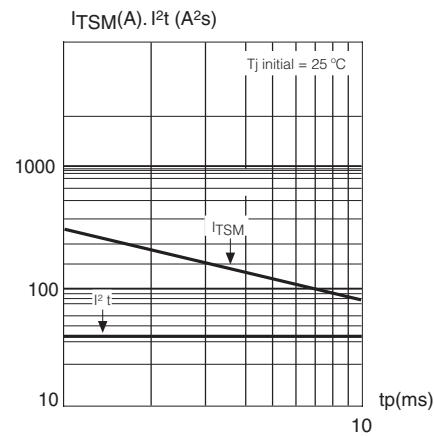


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width:  $t_p < 10$  ms, and corresponding value of  $I^2t$



## HIGH COMMUTATION TRIAC

Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

$I_{GT}, I_H, I_{L[Tj]} / I_{GT}, I_H, I_{L[Tj]} = 25^\circ\text{C}$

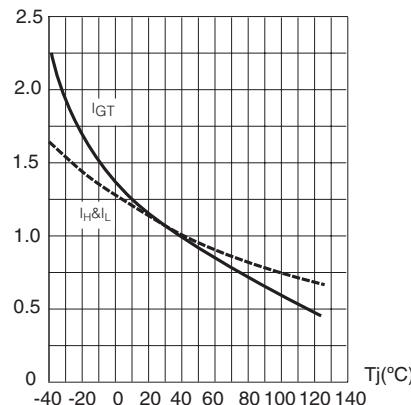
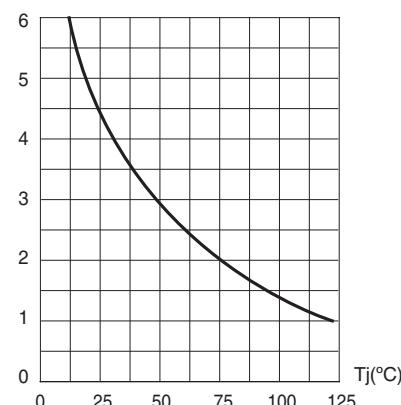


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature

$(dI/dt)_C [Tj] / (dI/dc)_C [Tj \text{ specified}]$



### PACKAGE MECHANICAL DATA

IPAK TO 251-AA

REF.	DIMENSIONS		
	Millimeters		
	Min.	Nominal	Max.
A	2.19	$2.30 \pm 0.11$	2.41
A1	0.89	$1.08 \pm 0.19$	1.27
b	0.50	$0.70 \pm 0.20$	0.90
b1	0.70	$0.92 \pm 0.22$	1.14
c	0.43	$0.51 \pm 0.08$	0.59
c2	0.43	$0.62 \pm 0.19$	0.81
D	5.40	$5.81 \pm 0.41$	6.22
D1	5.70	$5.90 \pm 0.20$	6.10
E	6.35	$6.54 \pm 0.19$	6.73
E1	5.20	$5.33 \pm 0.13$	5.46
e	2.25	$2.30 \pm 0.05$	2.35
L	7.50	$8.58 \pm 1.08$	9.66
L1	1.90	$2.10 \pm 0.20$	2.28
L3	0.89	$1.27 \pm 0.38$	1.65

Marking: type number  
Weight: 0.2 g